SN54LS07, SN74LS07, SN74LS17 HEX BUFFERS/DRIVERS WITH OPEN-COLLECTOR HIGH-VOLTAGE OUTPUTS SDLS021C - MAY 1990 - REVISED FEBRUARY 2004

- Convert TTL Voltage Levels to MOS Levels
- High Sink-Current Capability
- Input Clamping Diodes Simplify System Design
- Open-Collector Driver for Indicator Lamps and Relays

description/ordering information

These hex buffers/drivers feature high-voltage open-collector outputs to interface with high-level circuits or for driving high-current loads. They are

also characterized for use as buffers for driving TTL inputs. The 'LS07 devices have a rated output voltage of 30 V, and the SN74LS17 has a rated output voltage of 15 V. The maximum sink current is 30 mA for the SN54LS07 and 40 mA for the SN74LS07 and SN74LS17.

These circuits are compatible with most TTL families. Inputs are diode-clamped to minimize transmission-line effects, which simplifies design. Typical power dissipation is 140 mW, and average propagation delay time is 12 ns.

TA	PACI	KAGE [†]	ORDERABLE PART NUMBER	TOP-SIDE MARKING
	PDIP – N	Tube	SN74LS07N	SN74LS07N
	70°C SOIC – D	Tube	SN74LS07D	1.007
0°C to 70°C		Tape and reel	SN74LS07DR	LS07
	SOP – NS		SN74LS07NSR	74LS07
	SSOP – DB	Tape and reel	SN74LS07DBR	LS07

ORDERING INFORMATION

[†] Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

logic diagram (positive logic)





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SN54LS07 J PACKAGE					
SN74LS07, SN74LS17 D, DB, N, OR NS PACKAGE					
(TOP VIEW)					

1A [1Y [2A [2Y [3A [3Y [GND [1 2 3 4 5 6 7	σ	12 11] V _{CC}] 6A] 6Y] 5A] 5Y] 4A] 4Y
GND	1		8	

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schematic (each gate)



Resistor values shown are nominal.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Supply voltage, V _{CC} Input voltage, V _I (see Note 1)		
Output voltage, V_{Ω} (see Notes 1 and 2): SN54L		
SN74L	_S17	15 V
Package thermal impedance, θ_{JA} (see Note 3):	D package	
	DB package	
	N package	80°C/W
	NS package	
Storage temperature range,T _{stg}		\dots –65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. All voltage values are with respect to GND.

2. This is the maximum voltage that should be applied to any output when it is in the off state.

3. The package thermal impedance is calculated in accordance with JESD 51-7.



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recommended operating conditions (see Note 4)

			s	SN54LS07		SN74LS07 SN74LS17			UNIT
			MIN	NOM	MAX	MIN	NOM	MAX	
VCC	Supply voltage		4.5	5	5.5	4.75	5	5.25	V
VIH	High-level input voltage		2			2			V
VIL	Low-level input voltage				0.8			0.8	V
VOH		'LS07			30			30	
	High-level output voltage	SN74LS17						15	V
IOL	Low-level output current				30			40	mA
TA	Operating free-air temperature		-55		125	0		70	°C

NOTE 4: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST C	ONDITIONS [‡]	SN54	SN54LS07 SN74LS07 SN74LS17			UNIT	
				MIN MAX		MIN	MAX		
VIK	$V_{CC} = MIN,$	lj = – 12 mA			-1.5		-1.5	V	
			'LS07, V _{OH} = 30 V		0.25		0.25		
IОН	$V_{CC} = MIN,$	V _{IH} = 2 V	SN74LS17, V _{OH} = 15 V				0.25	mA	
	$V_{CC} = MIN,$ $V_{IL} = 0.8 V$		I _{OL} = 16 mA		0.4		0.4	V	
VOL		V _{IL} = 0.8 V	I _{OL} = MAX§		0.7		0.7		
Ц	V _{CC} = MAX,	V _I = 7 V	-		1		1	mA	
Чн	V _{CC} = MAX,	V _I = 2.4 V			20		20	μA	
۱ _{IL}	V _{CC} = MAX,	$V_{ } = 0.4 V$			-0.2		-0.2	mA	
Іссн	V _{CC} = MAX				14		14	mA	
ICCL	$V_{CC} = MAX$				45		45	mA	

[‡]For conditions shown as MIN or MAX, use the appropriate value specified under *recommended operating conditions*.

 I_{OL} = 30 mA for SN54 series parts and 40 mA for SN74 series parts.

switching characteristics, $V_{CC} = 5 V$, $T_A = 25^{\circ}C$ (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST (CONDITIONS	MIN	TYP	MAX	UNIT
^t PLH	•	Y D	R _L = 110 Ω,	C 15 pE		6	10	-
^t PHL	A	ſ		= 110 Ω, C _L = 15 pF		19	30	ns



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C. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control.

Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.

- D. S1 and S2 are closed for tpLH, tpHL, tpHZ, and tpLZ; S1 is open and S2 is closed for tpZH; S1 is closed and S2 is open for tpZL. E.
- Phase relationships between inputs and outputs have been chosen arbitrarily for these examples.
- F. All input pulses are supplied by generators having the following characteristics: PRR \leq 1 MHz, Z_O \approx 50 Ω , t_f \leq 1.5 ns, t_f \leq 2.6 ns.
- G. The outputs are measured one at a time, with one input transition per measurement.

Figure 1. Load Circuits and Voltage Waveforms



N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



NOTES:

- A. All linear dimensions are in inches (millimeters).B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- \triangle The 20 pin end lead shoulder width is a vendor option, either half or full width.



D (R-PDSO-G14)

PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in inches (millimeters).

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).

D. Falls within JEDEC MS-012 variation AB.



MECHANICAL DATA

PLASTIC SMALL-OUTLINE PACKAGE

0,51 0,35 ⊕0,25⊛ 1,27 8 14 0,15 NOM 5,60 8,20 5,00 7,40 \bigcirc Gage Plane ₽ 0,25 7 1 1,05 0,55 0°-10° Δ 0,15 0,05 Seating Plane — 2,00 MAX 0,10PINS ** 14 16 20 24 DIM 10,50 10,50 12,90 15,30 A MAX A MIN 9,90 9,90 12,30 14,70 4040062/C 03/03

NOTES: A. All linear dimensions are in millimeters.

NS (R-PDSO-G**)

14-PINS SHOWN

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



MECHANICAL DATA

MSSO002E - JANUARY 1995 - REVISED DECEMBER 2001

DB (R-PDSO-G**)

PLASTIC SMALL-OUTLINE

28 PINS SHOWN



NOTES: A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.
- D. Falls within JEDEC MO-150



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